Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.012”**

**ANODE**

**.0048”**

**SILICON OXIDE ALUMINUM**

**.012”**

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: .0048 x .0048”**

**Backside Potential: CATHODE**

**APPROVED BY: DK DIE SIZE .012” X .012” DATE: 10/21/21**

**MFG: DIONICS THICKNESS .006” P/N: 1N914B**

**DG 10.1.2**

#### Rev B, 7/1